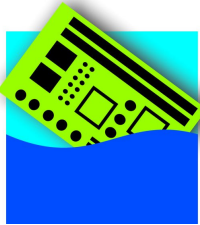


VIGON® A 250

Water-based defluxing agent for low pressure cleaning processes



VIGON® A 250 was specifically developed for low and medium pressure spray-in-air processes with long exposure times. VIGON® A 250 is a MPC® Technology based cleaning agent recommended for removing a wide range of flux residues from electronic assemblies. VIGON® A 250's mild formula is particularly gentle on all solder joints and materials.

Areas of application: PCB cleaning		Further information for this product:
Low solid flux residues	++	Technical Information Sheet 2: Removability overview list
Rosin - based flux residues	++	
Water soluble flux residues	++	Technical Information Sheet 3: Material compatibility overview
Solder paste (unsoldered)	+	
SMT or conductive adhesives	o	Application Recommendation: Initial process parameters recommendation
		MPC® Technology Sheet: Detailed information on the MPC® Technology

++ highly recommended, best results

+ recommended

o possible

Free-of-Charge Cleaning Trials at ZESTRON's Technical Centers



Free-of-charge cleaning trials can be performed at one of ZESTRON's Global Technical Centers. ZESTRON's European, North American and Asian Technical Centers feature spray-in-air, ultrasonic or spray-under-immersion processes. This provides an extensive overview on all available processes by leading international equipment manufacturers.



Upon completion of the cleaning trials, extensive analytical tests such as SIR and ionic residue measurements can be performed.

Please consult with ZESTRON's Application Technology Centers regarding future cleaning trials.

Advantages compared to other cleaning agents:

- Specifically developed for batch cleaning applications.
- Ability to remove a wide range of flux residues.
- Excellent material compatibility, even with long contact times.
- High bath loading capacity ensures extended bath life, low maintenance costs and reduced costs per cleaned part.
- Surfactant-free formulation eliminates the formation of white residues on cleaned parts and cleaning equipment and eliminates time-consuming surfactant monitoring.
- Mild formulation results in shiny solder joints and low ionic contamination values.

Please refer to the material compatibility list (Technical Information 3) prior to cleaning plastics.

Process	Cleaning	Rinsing	Drying
Spray-in-air (low to medium pressure)	VIGON® A 250	DI-water	Hot air or circulating air
Centrifugal/Ultrasonic Cleaning	VIGON® A 250	DI-water	Hot air or circulating air

Technical Data

Please note that the information above represents VIGON® A 250 at a 15 % concentration.

Density	(g/ccm) at 20°C/68°C	1
Surface tension	(mN/m) at 25°C/77°F	31.7
Boiling range	°C/°F	> 100 / 212
Flash point	°C/°F	None
pH-Value	10g/l H ₂ O	9.9
Vapor pressure	(mbar) at 20°C/68°F	20
Cleaning temperature	°C/°F	40 – 60 / 104 - 140
Solubility in water		Soluble
Application concentration	%	15 - 20
HMIS Rating	Health, Flammability, Reactivity	1 – 0 – 0

Lead-free Compliant:



VIGON® A 250 meets the new RoHS & WEEE guidelines as well as current worker safety standards and the actual applicable environmental requirements. Its formulation is free of any other banned hazardous substances.



Extensive lead-free defluxing with VIGON® A 250 was successfully completed by our Application Technology Centers. For further details please check our Technical Information Sheet 2.

Environmental, health and safety regulations:

VIGON® A 250 is water-based and biodegradable. The cleaning agent does not contain any halogenated compounds and is not considered as a hazardous material. No special precautions for handling of VIGON® A 250 are required.

Availability/Storage:

VIGON® A 250 is available as concentrate in 1L bottles, 5L, 25L canisters and 200L drums. Store VIGON® A 250 in the original container at a temperature between 41-86°F / 5 - 30°C. The product has a minimum shelf life of 5 years in factory sealed containers.

Cleaning Standards:

Cleaning with VIGON® A 250 was successfully tested and passed the current electronic manufacturing industry standards:

- Visual cleanliness in accordance with IPC-610A
- Ionic cleanliness in accordance with J-STD 001D
- Surface tension in accordance with IPC-TM 650 and DIN 32513
- Solderability according to J-STD 003

Alternative product recommendation:

For water-based defluxing of electronic assemblies in high pressure spray-in-air processes we recommend VIGON® A 201.